

ALUMINIUM VIA PROCESS

a) starting stack: aluminium + kapton / glue



b) aluminium chemical etching + plasma etching



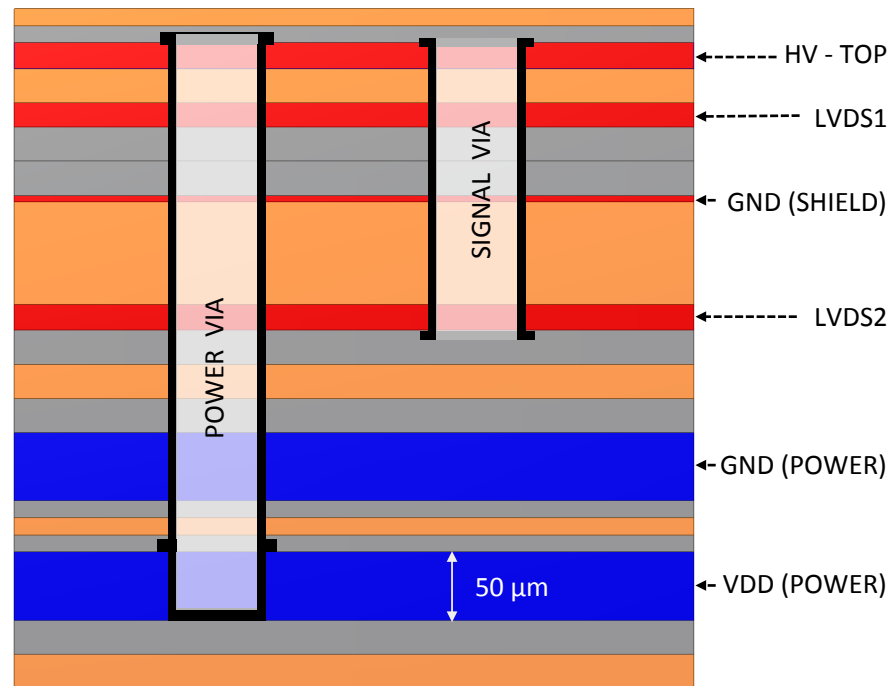
c) chrome (0.2 μm) + copper (2 μm) deposition



d) copper electroplating (20 μm)



e) copper etching: "copper drop" for via contact



Piralux / kapton

Copper

Glue

Aluminium

a)

b)